



# AUTOMATED CHEMICAL SOLUTIONS

Chemicals and Controllers for PWB Fabrication

## Product Overview

### **1/2 ETCH CR-2180**

#### **Copper Foil Reduction Process**

#### **Product Description**

The 1/2 ETCH CR-2180 is a hydrogen peroxide/sulfuric acid copper etching process designed to rapidly and evenly reduce copper foil thickness prior to the fine etching operations of HDI and BGA manufacturing processes. CR-2180 offers HDI and BGA manufacturers a cost-effective alternative to thin foil laminates by allowing them to accurately and reproducibly reduce 1/2-ounce foil to the optimal thickness for their given process. CR-2180 etches the copper uniformly and often produces a foil thickness with less variation than the starting vendor foil. CR-2180's hydrogen peroxide stabilizers virtually eliminate destabilization losses while etch accelerators and modifiers increase etch rate and improve surface topography.

#### **FEATURES**

- 💡 Produces thin foil laminates to process specific requirements
- 💡 Rate enhancing additives
- 💡 Etch modifiers

#### **BENEFITS**

- 💰 Saves money over the high cost of thin foil laminates and provides process specific foil thickness
- ⚙️ Increases etch rate without increasing consumption
- 👉 Improves surface topography and levels surface

#### **Storage**

Store in original containers above 40 °F.

#### **Safety**

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

#### **Notice**

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